

**Section**

MV Semi-conductor

**Application**Field  
Laboratory**PRODUCT BENEFITS**

No silicon needed  
 Fine tuning of the blade with a 'click' for each 1/10 mm  
 Very smooth finish over the insulation  
 Adjustable length of semiconductor cutback : 25-30-40 mm / 0,984-1,181-1,575 in

**TOOL CAPACITY**

<b>Diameter</b>	18 - 60 mm 0,709 - 2,362 inch
<b>Thickness capacity</b>	1,1 mm / 0,043 in
<b>Angle of the chamfer on the semiconductor</b>	8°
<b>Remaining length of the semiconductor</b>	25-30-40 mm / 0,984-1,181-1,575 in

**TOOL DIMENSIONS**

<b>Length</b>	235 mm
<b>Width</b>	125 mm
<b>Height</b>	90 mm
<b>Weight without box</b>	0,85 Kg
<b>Packaging</b>	None

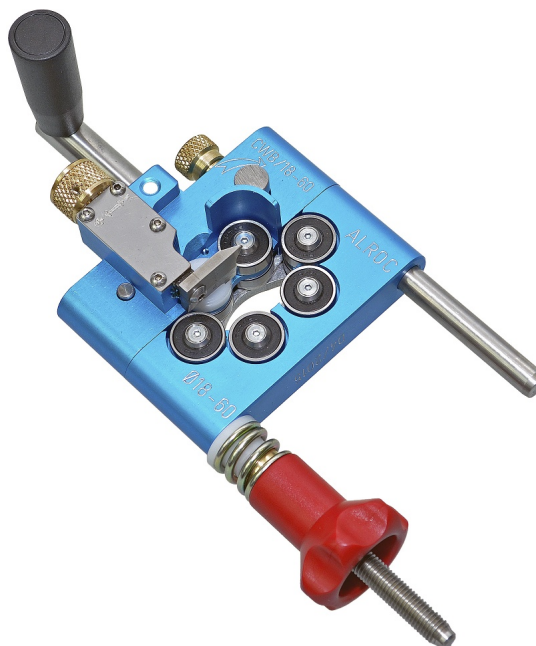
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## Tool to remove bonded semiconductor with chamfer on the semiconductor cutback

**TO DO WHAT**

The CWB/18-60 enables the user to easily remove the bonded semi-conductor with a chamfer on the transition, leaving a very smooth finish over the insulation  
 The CWB 18-60 works without silicone

**Options**

SGM - Large size pouch

**Spare part**

LCWB-SP2 - Spare blade for bonded semiconductor with chamfer 8°

**Associated tool**

LCWB-FEP - Spare blade for bonded semiconductor with chamfer 13°  
 GRI-RTE - Scraper for residues of bonded semiconductor screen with protection pouch  
 PG3HTA/2530 - Pliers for MV cables outer sheath  
 BRMRD1E - Tool to remove insulation

MV cables Tools

# CWB/18-60



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Thickness capacity	Angle of the chamfer on the semiconductor	Remaining length of the semiconductor	Length	Width	Height	
<b>CWB/18-60</b>	18 - 60 mm 0,709 - 2,362 in	1,1 mm / 0,043 in	8°	25-30-40 mm / 0,984-1,181-1,575 in	235 mm 9,252 in	125 mm 4,921 in	90 mm 3,543 in	none
<b>CWB/18-60-FEP</b>	18 - 60 mm 0,709 - 2,362 in	1,8 mm / 0,071 in	13°	25-30-40 mm / 0,984-1,181-1,575 in	235 mm 9,252 in	125 mm 4,921 in	90 mm 3,543 in	none